Enhancement mode

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

## 2SK2749

:  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : R_{DS}\ (ON) = 1.6\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 5.0\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 720\ V) \\ \end{array}$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	900	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	900	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	$I_{D}$	7	А	
Diain current	Pulse (Note 1)	$I_{DP}$	21		
Drain power dissipatio	n (Tc = 25°C)	$P_{D}$	150	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	682	mJ	
Avalanche current		I <sub>AR</sub>	7	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Unit: mm

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Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 25.5 mH,  $I_{AR} = 7 \text{ A}$ ,  $R_G = 25 \Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



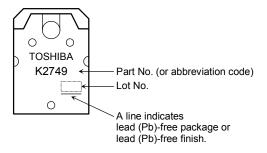
## **Electrical Characteristics (Ta = 25°C)**

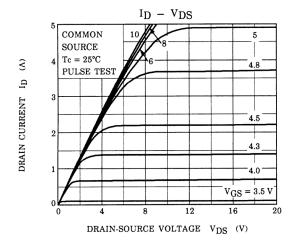
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V		_	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	$I_G = \pm 10 \mu A, V_{DS} = 0 V$	±30	_	-	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 720 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	900	_	-	V
Gate threshold v	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.5 A	_	1.6	2.0	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.5 A	1.25	5.0	-	S
Input capacitano	e	C <sub>iss</sub>		_	1500	-	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		30	-	pF
Output capacitance		C <sub>oss</sub>			140	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OV}$ $V_{DD}$ $V_{DD}$ $V_{DD}$	_	35	_	- ns
	Turn-on time	t <sub>on</sub>		_	80	_	
	Fall time	t <sub>f</sub>		_	50	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu s$		220	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$		55	_	nC
Gate-source charge		Q <sub>gs</sub>			30	_	
Gate-drain ("miller") Charge		$Q_{gd}$			25	_	

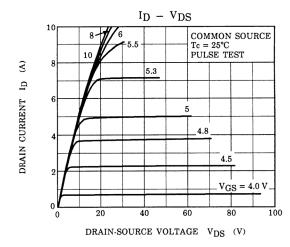
## Source-Drain Ratings and Characteristics (Ta = 25°C)

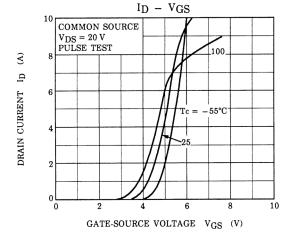
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	-	_	_	7	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	-	_	21	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 7 A, V <sub>GS</sub> = 0 V	_	_	-1.9	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 7 A, V <sub>GS</sub> = 0 V dI <sub>DR</sub> / dt = 100 A / μs	1	1400		ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 100 A / μs	_	14	_	μC

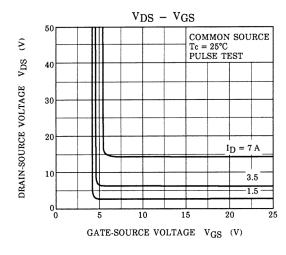
## Marking

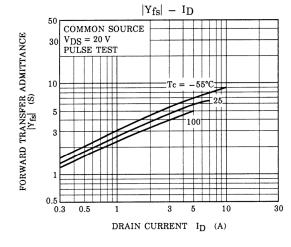


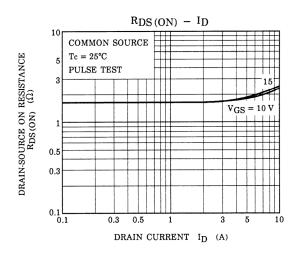


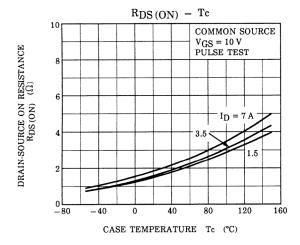


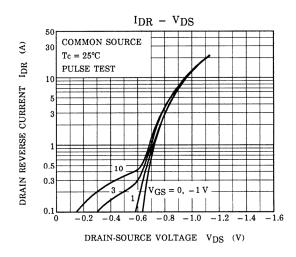


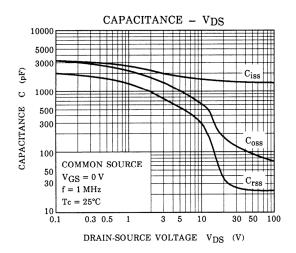


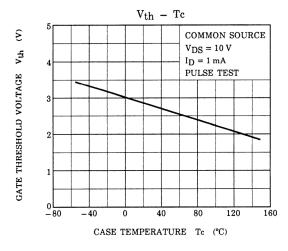


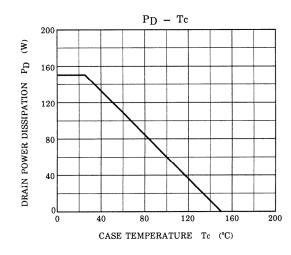


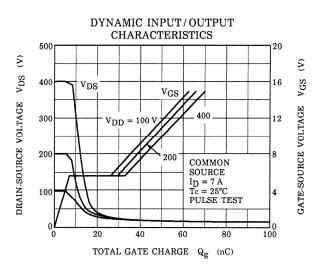




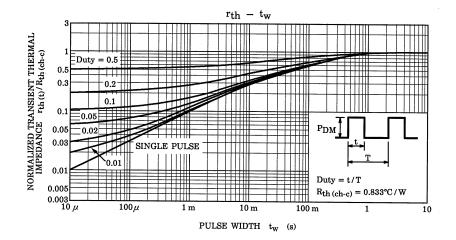


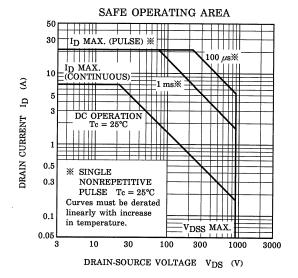


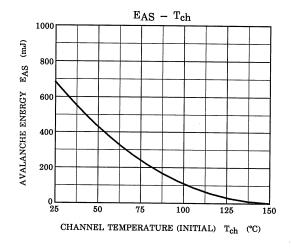


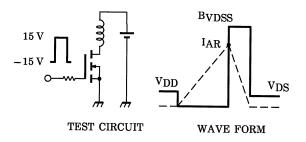


4









$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 25.5~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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